

# XPedite2570

3U VPX Xilinx Kintex® UltraScale™ FPGA-Based Fiber-Optic I/O Module

- ▶ Xilinx Kintex® UltraScale™ XCKU115 FPGA
- ▶ 3U VPX (VITA 46) module
- ▶ Twelve 10.3125 Gb/s optical transmitter links
- ▶ Twelve 10.3125 Gb/s optical receiver links
- ▶ 8 GB of DDR4-2400 ECC SDRAM in two channels
- ▶ Non-volatile FPGA dual quad-SPI configuration flash
- ▶ x8 PCI Express Gen3 to P1.A
- ▶ Two GTH-capable High-Speed Serial (HSS) lanes
- ▶ 44 LVDS GPIO
- ▶ Ten single-ended (SE) GPIO
- ▶ FPGA Development Kit (FDK)
- ▶ Linux drivers



## XPedite2570

The XPedite2570 is a high-performance, reconfigurable, conduction- or air-cooled, 3U VPX, FPGA processing module based on the Xilinx Kintex® UltraScale™ family of FPGAs. With multiple high-speed fabric interfaces, x8 PCI Express Gen3, 12 high-speed fiber-optic transceivers, and 8 GB of DDR4-2400 SDRAM in two channels, the XPedite2570 is ideal for customizable, high-bandwidth, signal-processing applications.

The XPedite2570 is a reconfigurable FPGA resource designed to meet the demands of high-bandwidth applications such as packet processing, signal processing, and DSP-intensive applications. It features 12 rugged, protocol-independent fiber optic transceivers operating at up to 10.3125 Gb/s, along with 8 GB of DDR4 ECC SDRAM in two independent channels capable of up to 38 GB/s aggregate bandwidth. The XPedite2570 has several options for high-performance backplane I/O, including a x8 Gen3 PCI Express interface, dual GTH transceivers with a maximum data rate of 16.375 Gb/s, and up to 44 LVDS transceivers for user I/O.

The XPedite2570 incorporates 12 high-data-rate, protocol-independent fiber-optic receivers. The fiber-optic receivers utilize 50/125 μm multi-mode fiber with MT connectors, which can easily be connected to the backplane (VITA 66). The fiber-optic receivers are qualified over the full -40°C to +85°C industrial temperature range for reliable performance in extreme environments.

The XPedite2570 is designed to be a user-programmable FPGA resource, using the powerful Xilinx Kintex® UltraScale™ XCKU115 FPGA to support high-performance signal processing, sensor I/O, data acquisition, data recording, and linking systems in a range of protocols.

The XPedite2570 provides a high-performance, feature-rich solution capable of interfacing to and processing streaming data from a wide variety of sensors. The X-ES FPGA Development Kit (FDK) is provided to support the requirements of high-performance, real-time, embedded, streaming-data applications and simplify FPGA development. X-ES' FDK includes IP blocks, HDL, test benches, Linux drivers, and complete example designs for the XPedite2570.

# X-ES

Extreme Engineering Solutions

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## Extreme Engineering Solutions

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**FPGA**

- Xilinx Kintex® UltraScale™ XCKU115 FPGA for high-performance logic and DSP applications
- 8 GB of DDR4-2400 ECC SDRAM in two channels
- 1 GBit of configuration NOR Flash

**Optical Interfaces**

- 12-channel transmitter and receiver modules
- 14 Gb/s max line rate
- Socketed Samtec FireFly optics
- I<sup>2</sup>C register interfaces
- Industrial temperature range

**VPX (VITA 46) P1 I/O**

- One x8 PCI Express Gen3 interface to P1.A
- Two additional GTH-capable High-Speed Serial (HSS) lanes
- Twelve LVDS and two single-ended GPIO

**VPX (VITA 46) P2 I/O**

- Thirty-Two LVDS and eight single-ended GPIO

**Development Support**

- X-ES FPGA Development Kit (FDK)
- Linux drivers

**Physical Characteristics**

- 3U VPX-REDI conduction- or air-cooled form factor
- Dimensions: 100 mm x 160 mm
- 0.8 in. pitch without solder-side cover
- 0.85 in. and 1.0 in. pitch with solder-side cover

**Environmental Requirements**

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 3, 5
- Conformal coating available as an ordering option

**Power Requirements**

- Power will vary based on configuration and usage. Please consult factory.

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C (maximum)
Vibration	0.002 g <sup>2</sup> /Hz (maximum), 5 to 2000 Hz	0.04 g <sup>2</sup> /Hz (maximum), 5 to 2000 Hz	0.1 g <sup>2</sup> /Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing

